

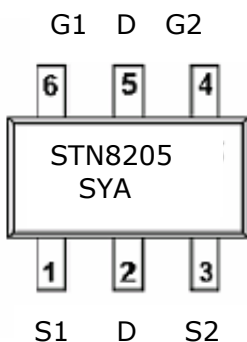
# STN8205D

## DESCRIPTION

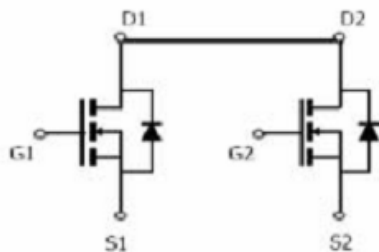
STN8205D is the dual N-Channel enhancement mode power field effect transistor which is produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, such as notebook computer power management and other battery powered circuits, where high-side switching is required.

## PIN CONFIGURATION

### TSOP-6



**S:** Subcontractor  
**Y:** Year  
**A:** Week Code



## FEATURE

- 20V/4.0A,  $R_{DS(ON)} = 30\text{m-ohm}@V_{GS} = 4.5\text{V}$
- 20V/3.4A,  $R_{DS(ON)} = 42\text{m-ohm}@V_{GS} = 2.5\text{V}$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional low on-resistance and maximum DC current capability
- TSOP-6 package design

## ORDERING INFORMATION

Part Number	Package	Part Marking
STN8205DST6RG	TSOP-6	SYA

※ Week Code Code : A ~ Z(1~26) ; a ~ z(27~52)

※ ST8205DST6RG ST6 : TSOP-6; R: Tape Reel ; G: Pb - Free

## STN8205D

## ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted )

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V <sub>DSS</sub>	20	V
Gate-Source Voltage		V <sub>GSS</sub>	+/-20	V
Continuous Drain Current (T <sub>J</sub> =150°C)	T <sub>A</sub> =25°C	I <sub>D</sub>	5.0	A
	T <sub>A</sub> =70°C		3.4	
Pulsed Drain Current		I <sub>DM</sub>	20	A
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	2	A
Power Dissipation	T <sub>A</sub> =25°C	P <sub>D</sub>	1.15	W
	T <sub>A</sub> =70°C		0.75	
Operation Junction Temperature		T <sub>J</sub>	150	°C
Storage Temperature Range		T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient		R <sub>θJA</sub>	100	°C/W

**STN8205D**
**ELECTRICAL CHARACTERISTICS ( Ta = 25°C Unless otherwise noted )**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.6		1.2	V
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=+/-20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=20V, V_{GS}=0V$			1	uA
		$V_{DS}=20V, V_{GS}=0V$ $T_J=85^\circ C$			5	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \leq 5V, V_{GS}=4.5V$	5			A
Drain-source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=4.0A$		0.025	0.030	$\Omega$
		$V_{GS}=2.5V, I_D=3.4A$		0.037	0.042	
Forward Transconductance	$g_{fs}$	$V_{DS}=5V, I_D=3.6A$		13		S
Diode Forward Voltage	$V_{SD}$	$I_S=1.6A, V_{GS}=0V$		0.8	1.2	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=10V, V_{GS}=4.5V, V_{DS}=2.8A$		10.5		nC
Gate-Source Charge	$Q_{gs}$			2.0		
Gate-Drain Charge	$Q_{gd}$			2.5		
Input Capacitance	$C_{iss}$	$V_{DS}=8V, V_{GS}=0V$ $f=1MHz$		805		pF
Output Capacitance	$C_{oss}$			155		
Reverse Transfer Capacitance	$C_{rss}$			122		
Turn-On Time	$T_{d(on)}$	$V_{DD}=10V, R_L=10\Omega, I_D=4.0A,$ $V_{GEN}=4.5V, R_G=6\Omega$		18		nS
	$t_r$			5		
Turn-Off Time	$T_{d(off)}$			45		
	$t_f$			22		